

# IS62C1024

## 128K x 8 HIGH-SPEED CMOS STATIC RAM

### FEATURES

- High-speed access time: 35, 45, 55, 70 ns
- Low active power: 450 mW (typical)
- Low standby power: 500  $\mu$ W (typical) CMOS standby
- Output Enable ( $\overline{OE}$ ) and two Chip Enable ( $\overline{CE1}$  and CE2) inputs for ease in applications
- Fully static operation: no clock or refresh required
- TTL compatible inputs and outputs
- Single 5V ( $\pm 10\%$ ) power supply

### DESCRIPTION

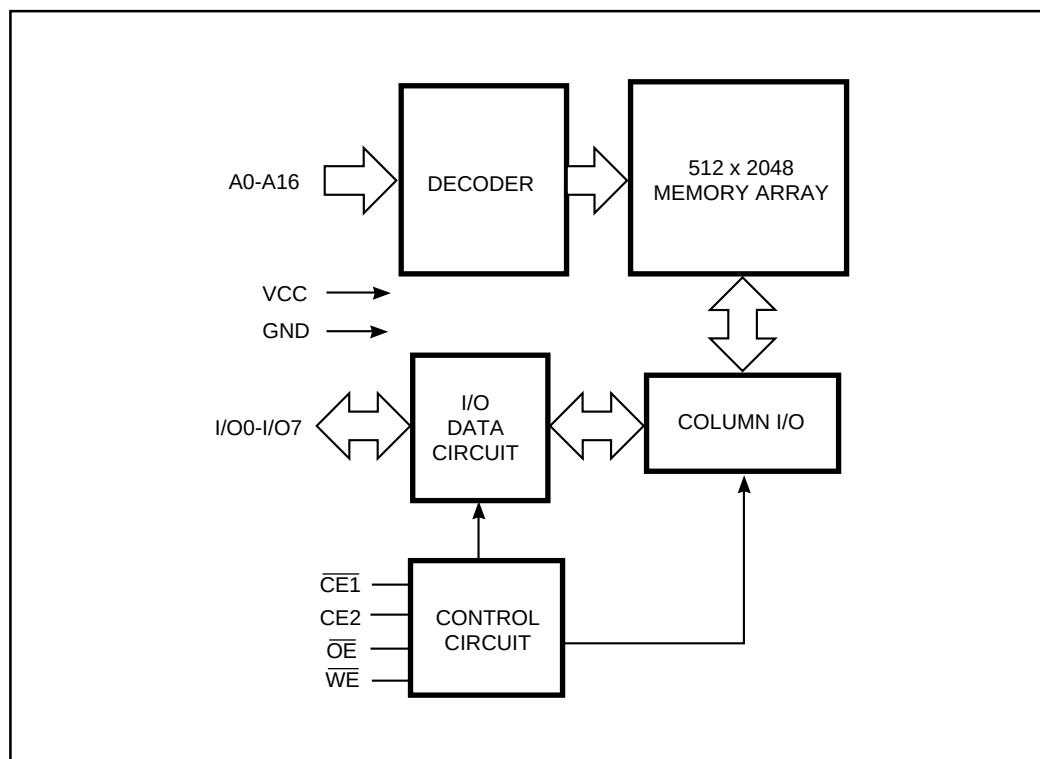
The *ICSI* IS62C1024 is a low power, 131,072-word by 8-bit CMOS static RAM. It is fabricated using *ICSI*'s high-performance CMOS technology. This highly reliable process coupled with innovative circuit design techniques, yields higher performance and low power consumption devices.

When  $\overline{CE1}$  is HIGH or CE2 is LOW (deselected), the device assumes a standby mode at which the power dissipation can be reduced by using CMOS input levels.

Easy memory expansion is provided by using two Chip Enable inputs,  $\overline{CE1}$  and CE2. The active LOW Write Enable ( $\overline{WE}$ ) controls both writing and reading of the memory.

The IS62C1024 is available in 32-pin 600mil DIP, 450mil SOP and 8\*20mm TSOP-1 packages.

### FUNCTIONAL BLOCK DIAGRAM



## PIN CONFIGURATION

### 32-Pin SOP and DIP

|      |    |    |      |
|------|----|----|------|
| NC   | 1  | 32 | VCC  |
| A16  | 2  | 31 | A15  |
| A14  | 3  | 30 | CE2  |
| A12  | 4  | 29 | WE   |
| A7   | 5  | 28 | A13  |
| A6   | 6  | 27 | A8   |
| A5   | 7  | 26 | A9   |
| A4   | 8  | 25 | A11  |
| A3   | 9  | 24 | OE   |
| A2   | 10 | 23 | A10  |
| A1   | 11 | 22 | CE1  |
| A0   | 12 | 21 | I/O7 |
| I/O0 | 13 | 20 | I/O6 |
| I/O1 | 14 | 19 | I/O5 |
| I/O2 | 15 | 18 | I/O4 |
| GND  | 16 | 17 | I/O3 |

## PIN CONFIGURATION

### 32-Pin 8x20mm TSOP-1

|     |    |    |      |
|-----|----|----|------|
| A11 | 1  | 32 | OE   |
| A9  | 2  | 31 | A10  |
| A8  | 3  | 30 | CE1  |
| A13 | 4  | 29 | I/O7 |
| WE  | 5  | 28 | I/O6 |
| CE2 | 6  | 27 | I/O5 |
| A15 | 7  | 26 | I/O4 |
| VCC | 8  | 25 | I/O3 |
| NC  | 9  | 24 | GND  |
| A16 | 10 | 23 | I/O2 |
| A14 | 11 | 22 | I/O1 |
| A12 | 12 | 21 | I/O0 |
| A7  | 13 | 20 | A0   |
| A6  | 14 | 19 | A1   |
| A5  | 15 | 18 | A2   |
| A4  | 16 | 17 | A3   |

## PIN DESCRIPTIONS

|           |                     |
|-----------|---------------------|
| A0-A16    | Address Inputs      |
| CE1       | Chip Enable 1 Input |
| CE2       | Chip Enable 2 Input |
| OE        | Output Enable Input |
| WE        | Write Enable Input  |
| I/O0-I/O7 | Input/Output        |
| Vcc       | Power               |
| GND       | Ground              |

## OPERATING RANGE

| Range      | Ambient Temperature | Vcc      |
|------------|---------------------|----------|
| Commercial | 0°C to +70°C        | 5V ± 10% |
| Industrial | -40°C to +85°C      | 5V ± 10% |

## TRUTH TABLE

| Mode            | WE | CE1 | CE2 | OE | I/O Operation | Vcc Current |
|-----------------|----|-----|-----|----|---------------|-------------|
| Not Selected    | X  | H   | X   | X  | High-Z        | Isb1, Isb2  |
| (Power-down)    | X  | X   | L   | X  | High-Z        | Isb1, Isb2  |
| Output Disabled | H  | L   | H   | H  | High-Z        | Icc         |
| Read            | H  | L   | H   | L  | DOUT          | Icc         |
| Write           | L  | L   | H   | X  | DIN           | Icc         |

**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

| Symbol            | Parameter                            | Value        | Unit |
|-------------------|--------------------------------------|--------------|------|
| V <sub>TERM</sub> | Terminal Voltage with Respect to GND | −0.5 to +7.0 | V    |
| T <sub>BIAS</sub> | Temperature Under Bias               | −10 to +85   | °C   |
| T <sub>STG</sub>  | Storage Temperature                  | −65 to +150  | °C   |
| P <sub>T</sub>    | Power Dissipation                    | 1.5          | W    |
| I <sub>OUT</sub>  | DC Output Current (LOW)              | 20           | mA   |

**Notes:**

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

**CAPACITANCE<sup>(1,2)</sup>**

| Symbol           | Parameter          | Conditions            | Max. | Unit |
|------------------|--------------------|-----------------------|------|------|
| C <sub>IN</sub>  | Input Capacitance  | V <sub>IN</sub> = 0V  | 6    | pF   |
| C <sub>OUT</sub> | Output Capacitance | V <sub>OUT</sub> = 0V | 8    | pF   |

**Notes:**

1. Tested initially and after any design or process changes that may affect these parameters.
2. Test conditions: T<sub>A</sub> = 25°C, f = 1 MHz, V<sub>CC</sub> = 5.0V.

**DC ELECTRICAL CHARACTERISTICS (Over Operating Range)**

| Symbol          | Parameter                        | Test Conditions                                   | Min.         | Max.                  | Unit |
|-----------------|----------------------------------|---------------------------------------------------|--------------|-----------------------|------|
| V <sub>OH</sub> | Output HIGH Voltage              | V <sub>CC</sub> = Min., I <sub>OH</sub> = −1.0 mA | 2.4          | —                     | V    |
| V <sub>OL</sub> | Output LOW Voltage               | V <sub>CC</sub> = Min., I <sub>OL</sub> = 2.1 mA  | —            | 0.4                   | V    |
| V <sub>IH</sub> | Input HIGH Voltage               |                                                   | 2.2          | V <sub>CC</sub> + 0.5 | V    |
| V <sub>IL</sub> | Input LOW Voltage <sup>(1)</sup> |                                                   | −0.3         | 0.8                   | V    |
| I <sub>LI</sub> | Input Leakage                    | GND ≤ V <sub>IN</sub> ≤ V <sub>CC</sub>           | Com.<br>Ind. | −5<br>10              | μA   |
| I <sub>LO</sub> | Output Leakage                   | GND ≤ V <sub>OUT</sub> ≤ V <sub>CC</sub>          | Com.<br>Ind. | −5<br>10              | μA   |

**Notes:**

1. V<sub>IL</sub> = −3.0V for pulse width less than 10 ns.

**POWER SUPPLY CHARACTERISTICS<sup>(1)</sup> (Over Operating Range)**

| Symbol           | Parameter                                        | Test Conditions                                                                                                                                               | −35 ns       |                 | −45 ns          |                 | −55 ns         |                | −70 ns         |                | Unit |
|------------------|--------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------------------------------|--------------|-----------------|-----------------|-----------------|----------------|----------------|----------------|----------------|------|
|                  |                                                  |                                                                                                                                                               | Min.         | Max.            | Min.            | Max.            | Min.           | Max.           | Min.           | Max.           |      |
| I <sub>CC</sub>  | V <sub>CC</sub> Dynamic Operating Supply Current | V <sub>CC</sub> = Max., $\overline{CE} = V_{IL}$<br>I <sub>OUT</sub> = 0 mA, f = f <sub>MAX</sub>                                                             | Com.<br>Ind. | —<br>150<br>160 | —<br>135<br>145 | —<br>120<br>130 | —<br>90<br>100 | —<br>90<br>100 | —<br>90<br>100 | —<br>90<br>100 | mA   |
| I <sub>SB1</sub> | TTL Standby Current (TTL Inputs)                 | V <sub>CC</sub> = Max.,<br>V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> , $\overline{CE1} \geq V_{IH}$ ,<br>or CE2 ≤ V <sub>IL</sub> , f = 0          | Com.<br>Ind. | —<br>40<br>60   | —<br>40<br>60   | —<br>40<br>60   | —<br>40<br>60  | —<br>40<br>60  | —<br>40<br>60  | —<br>40<br>60  | mA   |
| I <sub>SB2</sub> | CMOS Standby Current (CMOS Inputs)               | V <sub>CC</sub> = Max.,<br>$\overline{CE1} \geq V_{CC} - 0.2V$ ,<br>CE2 ≤ 0.2V, V <sub>IN</sub> > V <sub>CC</sub> − 0.2V,<br>or V <sub>IN</sub> ≤ 0.2V, f = 0 | Com.<br>Ind. | —<br>30<br>40   | —<br>30<br>40   | —<br>30<br>40   | —<br>30<br>40  | —<br>30<br>40  | —<br>30<br>40  | —<br>30<br>40  | mA   |

**Notes:**

1. At f = f<sub>MAX</sub>, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.

**READ CYCLE SWITCHING CHARACTERISTICS<sup>(1)</sup>** (Over Operating Range)

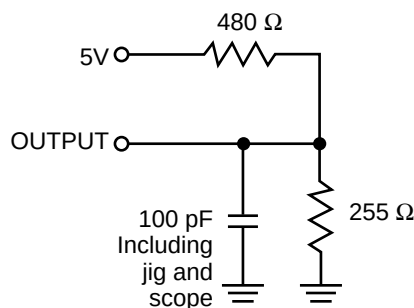
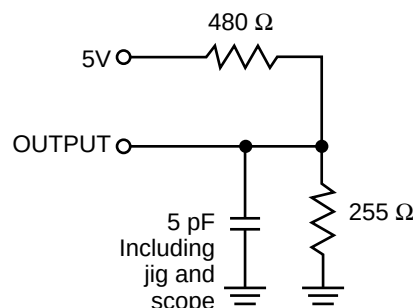
| Symbol                            | Parameter                                       | -35  |      | -45  |      | -55  |      | -70  |      | Unit |
|-----------------------------------|-------------------------------------------------|------|------|------|------|------|------|------|------|------|
|                                   |                                                 | Min. | Max. | Min. | Max. | Min. | Max. | Min. | Max. |      |
| t <sub>RC</sub>                   | Read Cycle Time                                 | 35   | —    | 45   | —    | 55   | —    | 70   | —    | ns   |
| t <sub>AA</sub>                   | Address Access Time                             | —    | 35   | —    | 45   | —    | 55   | —    | 70   | ns   |
| t <sub>OHA</sub>                  | Output Hold Time                                | 3    | —    | 3    | —    | 3    | —    | 3    | —    | ns   |
| t <sub>ACE1</sub>                 | $\overline{\text{CE}}1$ Access Time             | —    | 35   | —    | 45   | —    | 55   | —    | 70   | ns   |
| t <sub>ACE2</sub>                 | CE2 Access Time                                 | —    | 35   | —    | 45   | —    | 55   | —    | 70   | ns   |
| t <sub>DOE</sub>                  | $\overline{\text{OE}}$ Access Time              | —    | 10   | —    | 20   | —    | 25   | —    | 35   | ns   |
| t <sub>LZOE</sub> <sup>(2)</sup>  | $\overline{\text{OE}}$ to Low-Z Output          | 0    | —    | 0    | —    | 0    | —    | 0    | —    | ns   |
| t <sub>HZOE</sub> <sup>(2)</sup>  | $\overline{\text{OE}}$ to High-Z Output         | 0    | 10   | 0    | 15   | 0    | 20   | 0    | 25   | ns   |
| t <sub>LZCE1</sub> <sup>(2)</sup> | $\overline{\text{CE}}1$ to Low-Z Output         | 3    | —    | 5    | —    | 7    | —    | 10   | —    | ns   |
| t <sub>LZCE2</sub> <sup>(2)</sup> | CE2 to Low-Z Output                             | 3    | —    | 5    | —    | 7    | —    | 10   | —    | ns   |
| t <sub>HZCE</sub> <sup>(2)</sup>  | $\overline{\text{CE}}1$ or CE2 to High-Z Output | 0    | 10   | 0    | 15   | 0    | 20   | 0    | 25   | ns   |

**Notes:**

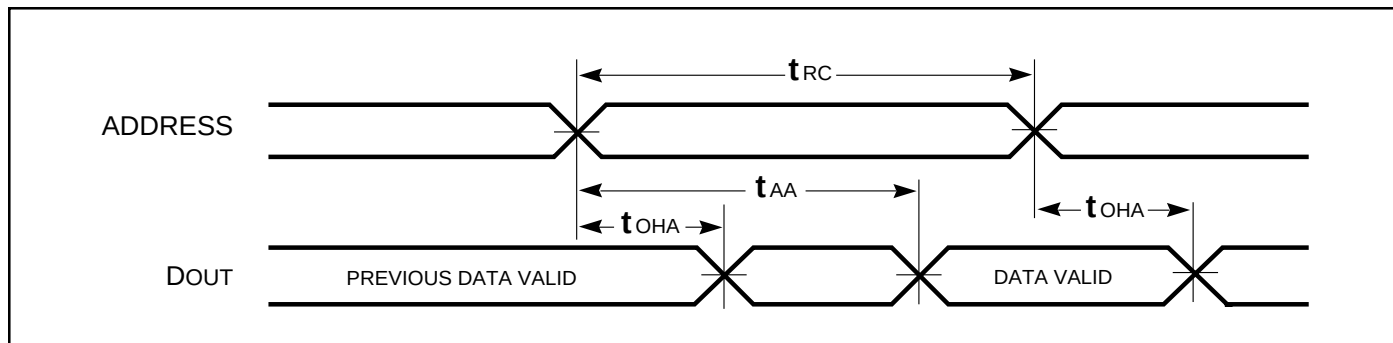
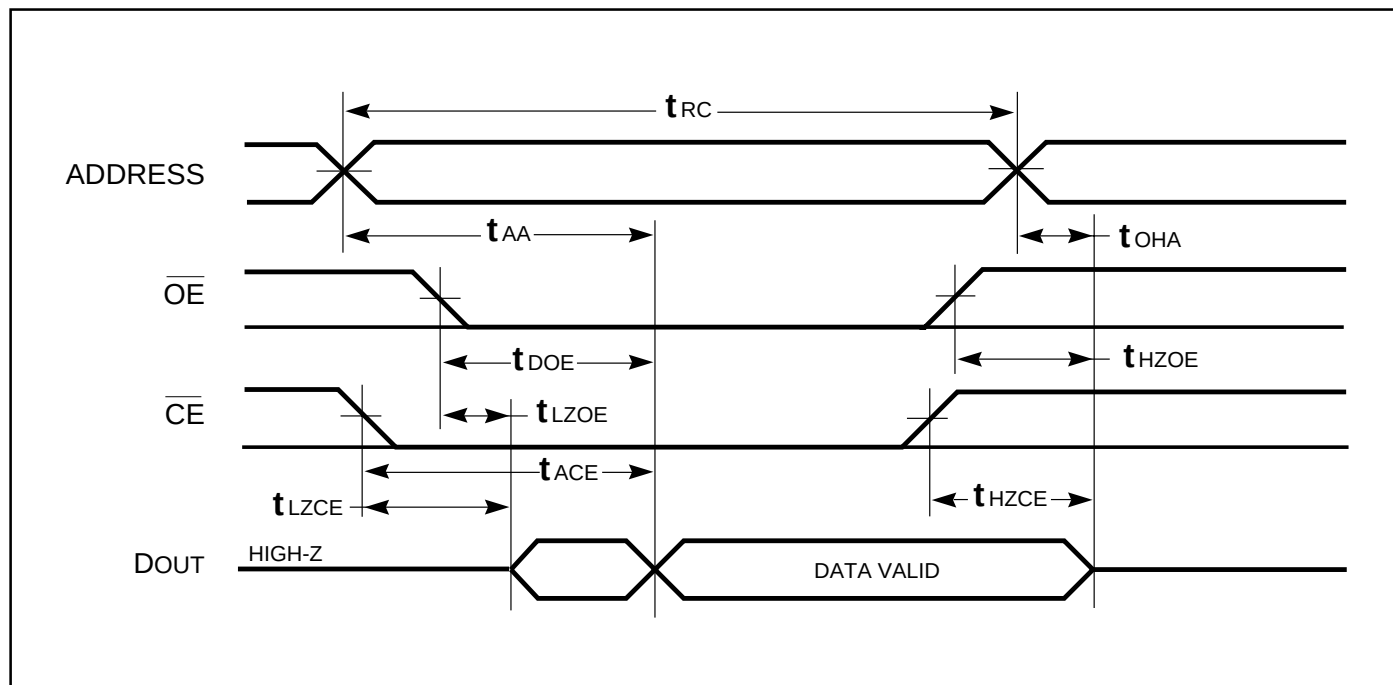
- Test conditions assume signal transition times of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1a.
- Tested with the load in Figure 1b. Transition is measured  $\pm 500$  mV from steady-state voltage. Not 100% tested.

**AC TEST CONDITIONS**

| Parameter                                   | Unit                  |
|---------------------------------------------|-----------------------|
| Input Pulse Level                           | 0V to 3.0V            |
| Input Rise and Fall Times                   | 5 ns                  |
| Input and Output Timing and Reference Level | 1.5V                  |
| Output Load                                 | See Figures 1a and 1b |

**AC TEST LOADS**

**Figure 1a.**

**Figure 1b.**

## AC WAVEFORMS

READ CYCLE NO. 1<sup>(1,2)</sup>READ CYCLE NO. 2<sup>(1,3)</sup>**Notes:**

1.  $\overline{WE}$  is HIGH for a Read Cycle.
2. The device is continuously selected.  $\overline{OE}$ ,  $\overline{CE1} = V_{IL}$ ,  $CE2 = V_{IH}$ .
3. Address is valid prior to or coincident with  $\overline{CE1}$  LOW and  $CE2$  HIGH transitions.

## WRITE CYCLE SWITCHING CHARACTERISTICS<sup>(1,3)</sup> (Over Operating Range, Standard and Low Power)

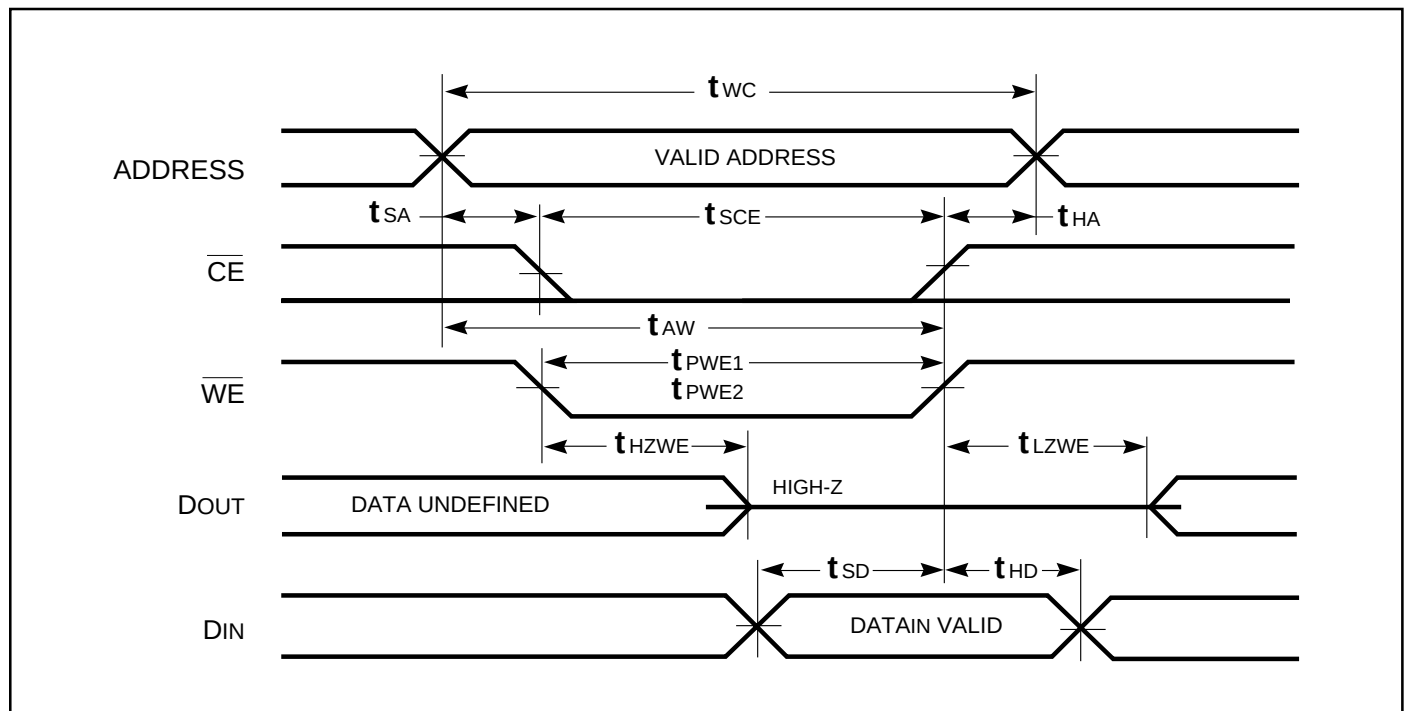
| Symbol           | Parameter                            | -35  |      | -45  |      | -55  |      | -70  |      | Unit |
|------------------|--------------------------------------|------|------|------|------|------|------|------|------|------|
|                  |                                      | Min. | Max. | Min. | Max. | Min. | Max. | Min. | Max. |      |
| $t_{WC}$         | Write Cycle Time                     | 35   | —    | 45   | —    | 55   | —    | 70   | —    | ns   |
| $t_{SCE1}$       | $\overline{CE1}$ to Write End        | 25   | —    | 35   | —    | 50   | —    | 60   | —    | ns   |
| $t_{SCE2}$       | CE2 to Write End                     | 25   | —    | 35   | —    | 50   | —    | 60   | —    | ns   |
| $t_{AW}$         | Address Setup Time to Write End      | 25   | —    | 35   | —    | 45   | —    | 60   | —    | ns   |
| $t_{HA}$         | Address Hold from Write End          | 0    | —    | 0    | —    | 0    | —    | 0    | —    | ns   |
| $t_{SA}$         | Address Setup Time                   | 0    | —    | 0    | —    | 0    | —    | 0    | —    | ns   |
| $t_{PWE}^{(4)}$  | $\overline{WE}$ Pulse Width          | 25   | —    | 35   | —    | 40   | —    | 50   | —    | ns   |
| $t_{SD}$         | Data Setup to Write End              | 20   | —    | 25   | —    | 25   | —    | 30   | —    | ns   |
| $t_{HD}$         | Data Hold from Write End             | 0    | —    | 0    | —    | 0    | —    | 0    | —    | ns   |
| $t_{HZWE}^{(2)}$ | $\overline{WE}$ LOW to High-Z Output | —    | 10   | —    | 15   | —    | 20   | —    | 25   | ns   |
| $t_{LZWE}^{(2)}$ | $\overline{WE}$ HIGH to Low-Z Output | 3    | —    | 5    | —    | 5    | —    | 5    | —    | ns   |

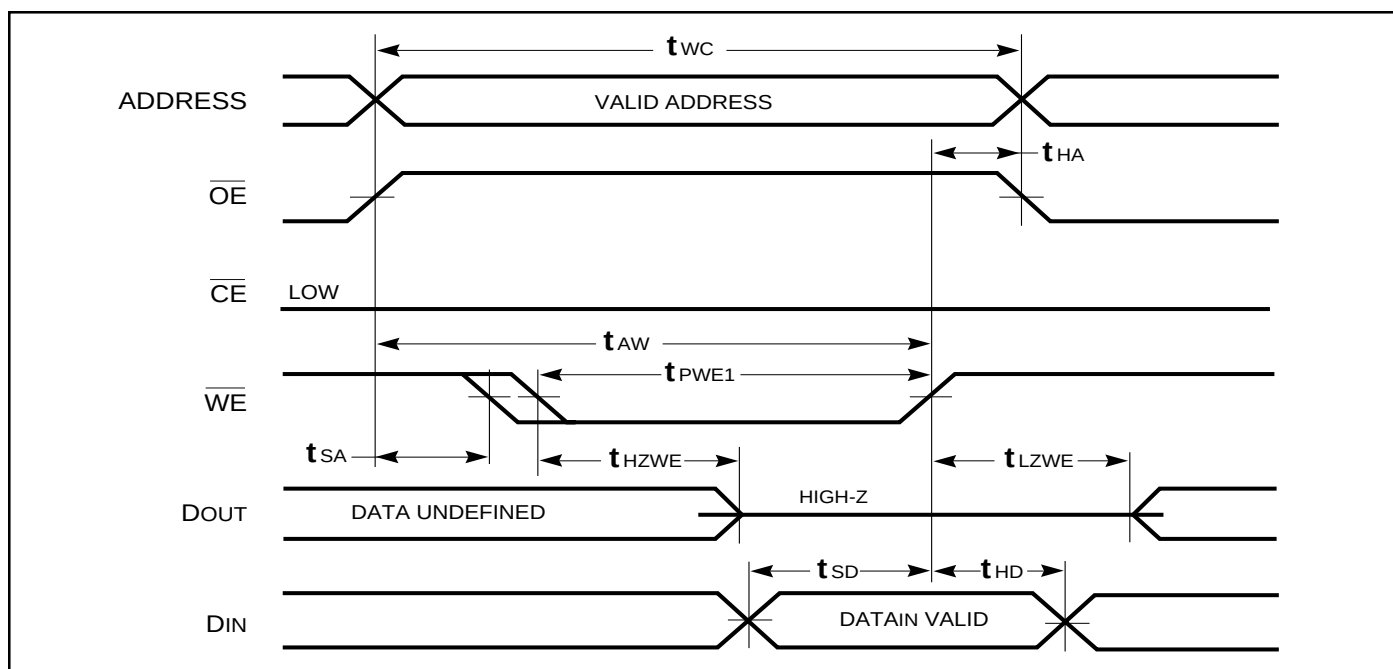
### Notes:

1. Test conditions assume signal transition times of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V and output loading specified in Figure 1a.
2. Tested with the load in Figure 1b. Transition is measured  $\pm 500$  mV from steady-state voltage. Not 100% tested.
3. The internal write time is defined by the overlap of  $\overline{CE1}$  LOW, CE2 HIGH and  $\overline{WE}$  LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the Write.
4. Tested with  $\overline{OE}$  HIGH.

## AC WAVEFORMS

### WRITE CYCLE NO. 1 ( $\overline{WE}$ Controlled)<sup>(1,2)</sup>



**WRITE CYCLE NO. 2 ( $\overline{CE1}$ , CE2 Controlled)<sup>(1,2)</sup>**

**Notes:**

1. The internal write time is defined by the overlap of  $\overline{CE1}$  LOW, CE2 HIGH and  $\overline{WE}$  LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the Write.
2. I/O will assume the High-Z state if  $\overline{OE} = V_{IH}$ .

**ORDERING INFORMATION****Commercial Range: 0°C to +70°C**

| Speed (ns) | Order Part No. | Package       |
|------------|----------------|---------------|
| 35         | IS62C1024-35W  | 600mil DIP    |
| 35         | IS62C1024-35Q  | 450mil SOP    |
| 35         | IS62C1024-35T  | 8*20mm TSOP-1 |
| 45         | IS62C1024-45W  | 600mil DIP    |
| 45         | IS62C1024-45Q  | 450mil SOP    |
| 45         | IS62C1024-45T  | 8*20mm TSOP-1 |
| 55         | IS62C1024-55W  | 600mil DIP    |
| 55         | IS62C1024-55Q  | 450mil SOP    |
| 55         | IS62C1024-55T  | 8*20mm TSOP-1 |
| 70         | IS62C1024-70W  | 6600mil DIP   |
| 70         | IS62C1024-70Q  | 450mil SOP    |
| 70         | IS62C1024-70T  | 8*20mm TSOP-1 |

**ORDERING INFORMATION****Industrial Range: -40°C to +85°C**

| Speed (ns) | Order Part No. | Package       |
|------------|----------------|---------------|
| 35         | IS62C1024-35WI | 600mil DIP    |
| 35         | IS62C1024-35QI | 450mil SOP    |
| 35         | IS62C1024-35TI | 8*20mm TSOP-1 |
| 45         | IS62C1024-45WI | 600mil DIP    |
| 45         | IS62C1024-45QI | 450mil SOP    |
| 45         | IS62C1024-45TI | 8*20mm TSOP-1 |
| 55         | IS62C1024-55WI | 600mil DIP    |
| 55         | IS62C1024-55QI | 450mil SOP    |
| 55         | IS62C1024-55TI | 8*20mm TSOP-1 |
| 70         | IS62C1024-70WI | 600mil DIP    |
| 70         | IS62C1024-70QI | 450mil SOP    |
| 70         | IS62C1024-70TI | 8*20mm TSOP-1 |

***Integrated Circuit Solution Inc.***

HEADQUARTER:

NO.2, TECHNOLOGY RD. V, SCIENCE-BASED INDUSTRIAL PARK,  
HSIN-CHU, TAIWAN, R.O.C.

TEL: 886-3-5780333

Fax: 886-3-5783000

BRANCH OFFICE:

7F, NO. 106, SEC. 1, HSIN-TAI 5<sup>TH</sup> ROAD,  
HSICHIH TAIPEI COUNTY, TAIWAN, R.O.C.

TEL: 886-2-26962140

FAX: 886-2-26962252

<http://www.icsi.com.tw>